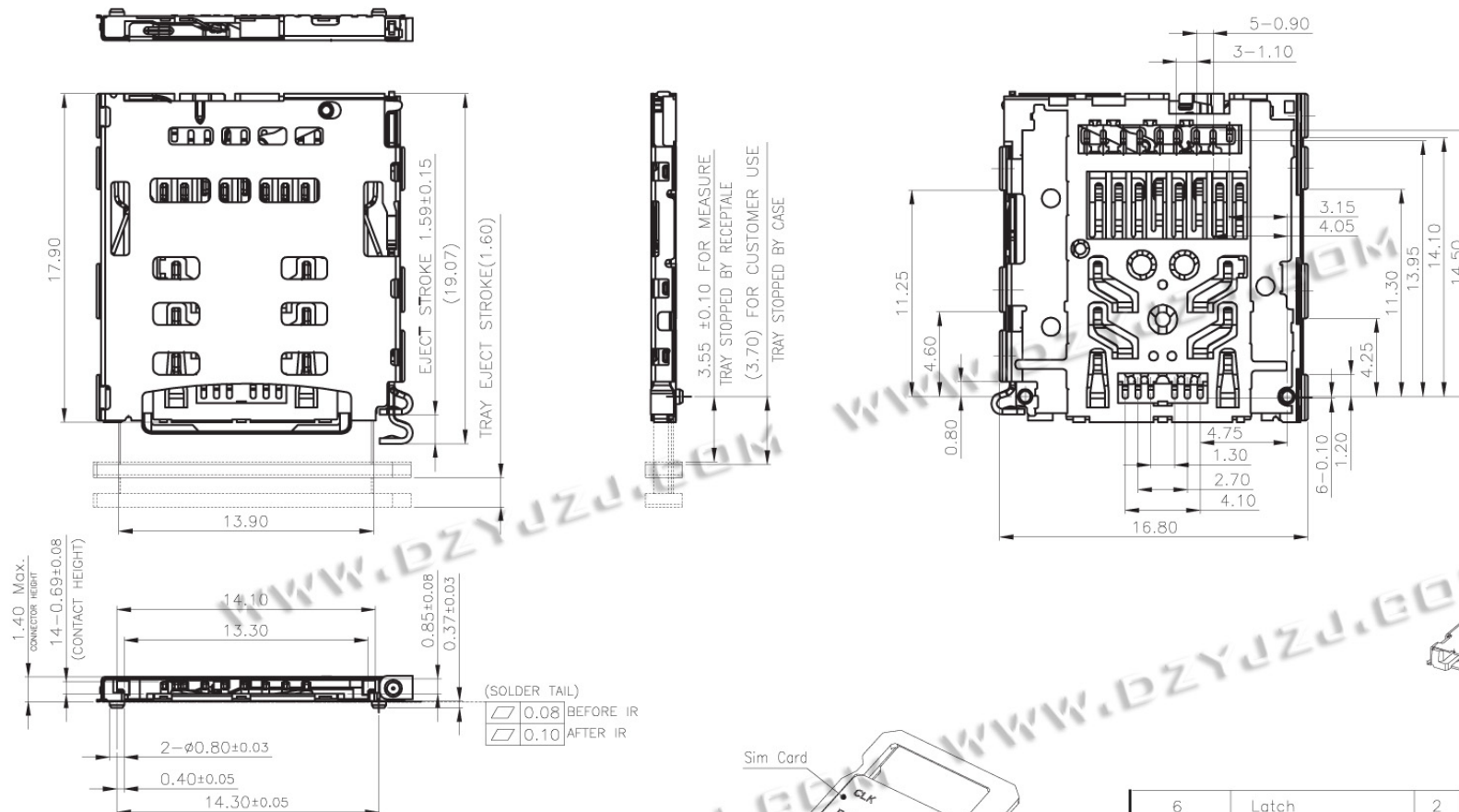




NOTES:

1. FINISH

1-1. CONTACT:
CONTACT AREA: Au 10u' Min.; SW AREA: Au 5u' Min;
GOLD PLATING ON SOLDER AREA, 3u' Min.

1-2. SHELL:
SW AREA: 3u' Min.; SOLDER AREA: Au 3u' Min.

2. ELECTRICAL REQUIREMENTS:

2-1. CURRENT RATING: 0.3A PER PIN.
2-2. CONTACT RESISTANCE: 60 mOhm MAX. AFTER TEST:100 mOhm MAX
SWITCH RESISTANCE : 100 mOhm MAX. AFTER TEST:150 mOhm MAX
2-3. INSULATION RESISTANCE: 1000 MOhm MIN.200 VDC FOR 1 MINUTE.
2-4. WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.

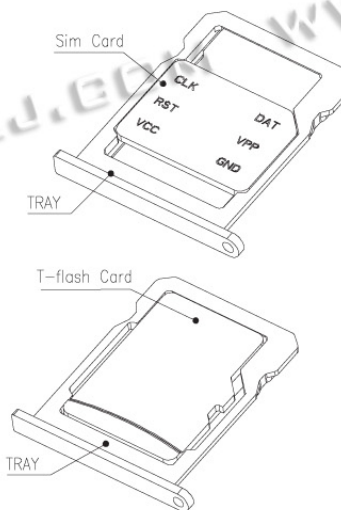
3. MECHANICAL REQUIREMENTS:

3-1. TRAY MATING FORCE: 0.2~ 1.0kgf.; TRAY UNMATING FORCE: 0.4~1.0kgf
OPERATING FORCE: 0.4~1.0 kgf.
THE RESORPTION DISTANCE OF THE TRAY : 0.4mm MIN

3-2. DURABILITY: 3,000 CYCLES MIN.

4. ENVIRONMENT REQUIREMENTS:

4-1. OPERATING TEMP.: -30°C TO +85°C
4-2. STORAGE TEMPERATURE: -40°C TO +85°C
5. UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE IN mm.
6. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY
PRODUCT DETAILS & AVAILABILITY.



6	Latch	2	④ SUS301-Γ	NO PLATING
5	CAM	1	SUS304-H	NO PLATING
4	LEVER	1	SUS301-H	NO PLATING
3	SHELL	1	SUS301-H	SWITCH AREA: Au 3u' min. SOLDER AREA: Au 3u' min.
2	I/M HOUSING	1	LCP	BLACK COLOR, UL94 V-0
1	CONTACT	1	NKT322-EH	CONTACT AREA: Au 10u' min. SWITCH AREA: Au 5u' min. SOLDER AREA: Au 3u' min.
ITEM	PART NAME	Q'TY	MATERIAL	FINISH

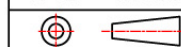


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TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X' ±2" X.X' ±0.5"



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

SIM CARD 1.4H 二选一卡座

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC28-2IN122-140

MOLD NO.

APPROVED BY:

邱国夷

DATE :

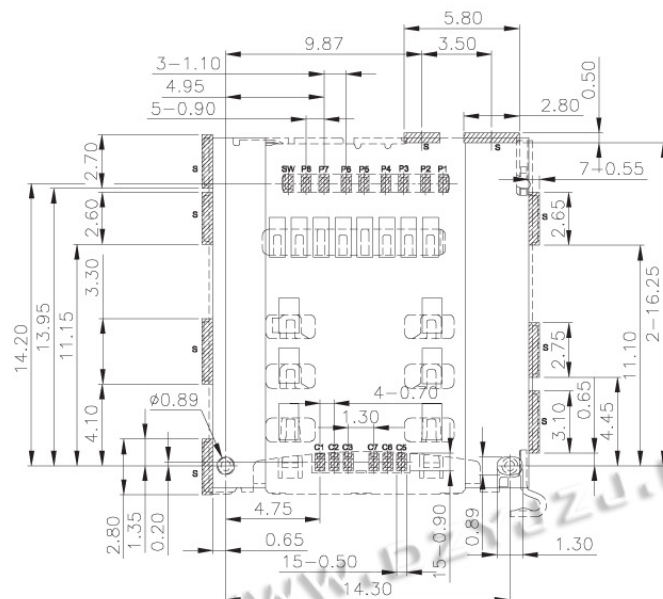
2014-02-23

DRAW NO:

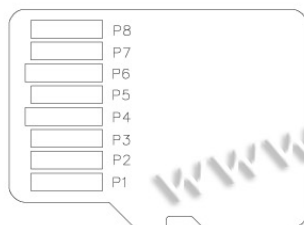
HYC-IN116072817

SHEET NO.

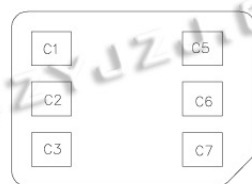
1 OF 1



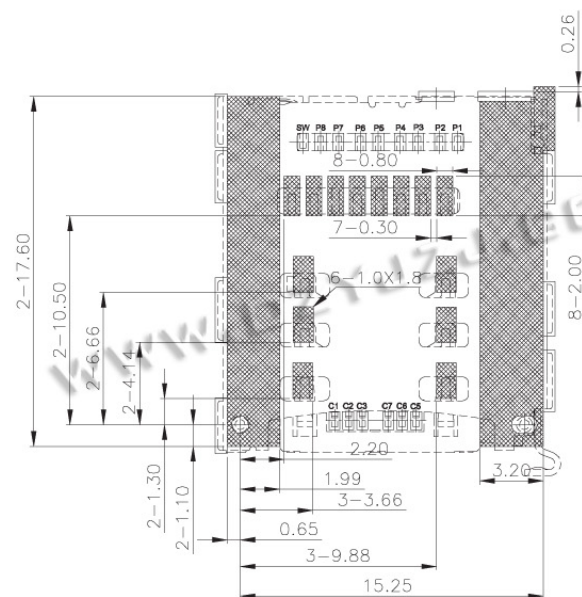
RECOMMENDED PCB LAYOUT(SOLDER AREA)
(TOLERANCE: ± 0.05)
PASTE BOARD THICKNESS 0.10mm.
SOLDER AREA



MSD CARD ELECTRICAL



NANO SIM CARD ELECTRICAL



RECOMMENDED PCB LAYOUT(NO PATTERNS)
(TOLERANCE: ± 0.05)
NO PATTERNS

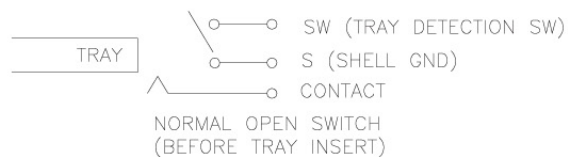
CONNECTOR PIN ASSIGNMENT:

ITEM	FUNCTION
MSD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
SW	TRAY DETECTION SW
S	SHELL GND
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

CARD PIN ASSIGNMENT:

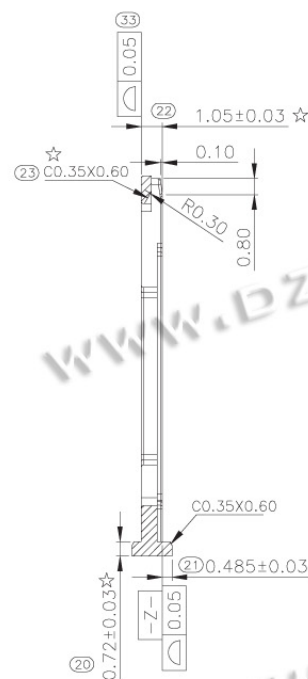
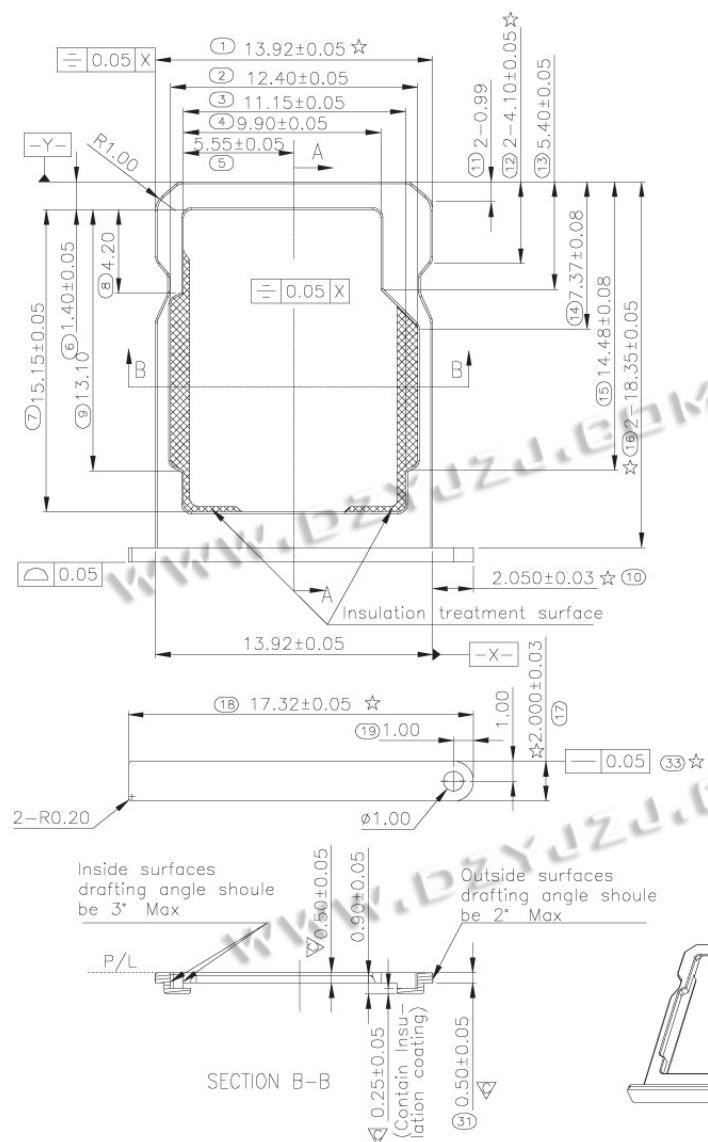
ITEM	FUNCTION
MSD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

CIRCUIT DIAGRAM FOR DETECT SWITCHES



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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X." ± 2 " X.X" ± 0.5 "	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SIM CARD 1.4H 二选一卡座
UNIT: mm [inch]	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC28-2IN122-140
SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	DRAW NO: HYC-IN116072817
			SHEET NO. 1 OF 1



SECTION A-A

NOTES: 1.Material: SUS17-4PH

2.Finish: Referce to customer request;

The roughness ∇ of all surfaces should meet $Ra < 0.5\mu m$; $Rz < 4.0\mu m$

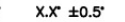
3.Harmful material control please follow "SS-00259-1"

4.The dimension marked ☆ should be checked by QC and process engineer,and should also check the CPK data.

3	REEL	PLOYSTYRENE
2	COVER TAPE	PLOYSTYRENE
1	CARRIER TAPE	THERMOPLASTIC
ITEM	P/N	MATERIAL



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TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2° X.X° ±0.5°				SIM CARD 1.4H 二选一卡座	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC28-2IN122-140
		马跃	2014-02-23	MOLD NO.	
				DRAW NO:	HYC-IN116072817
SCALE:1:1	SIZE: A4	APPROVED BY:	DATE :	SHEET NO.	1 OF 1
		邱国夷	2014-02-23		